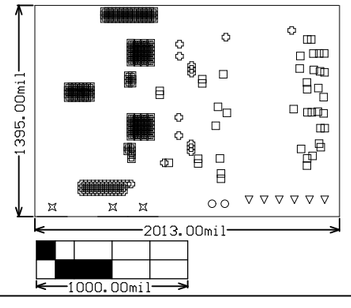
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4 High Tg	4.60mil	4.8	
5	MidLayer1	Copper	2.80mil		
6	Dielectric2	FR-4 High Tg	10.60mil	4.8	
7	MidLayer2	Copper	2.80mil		
8	Dielectric3	FR-4 High Tg	4.60mil	4.8	
9	Bottom Layer	Copper	2.80mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER 31 MIL
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



① Please fill and plate vias with 12.1 mil hole size

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
□	41	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⌬	51	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
◘	160	12.10mil (0.307mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
▽	6	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	3	65.00mil (1.651mm)	PTH	Round	Top Layer - Bottom Layer	
	263 Total					

TEXAS INSTRUMENTS

PROJECT TITLE: LMG3410-HB-EVM
DESIGNED FOR: General Release
FILE NAME: SV601254E.PcbDoc

	BOARD #: SV601254	REV: E	SVN REV: Not In VersionControl
[redacted]			
PLOT NAME = Fabrication Drawing	GENERATED : 4/4/2017 2:25:44 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Eric Faraci, Ted Chen	Eric Faraci, Ted Chen
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368